



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN20210730004.1
Qualify additional Assembly site for select SOT devices
Change Notification / Sample Request

Date: August 02, 2021
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team
SC Business Services

20210730004.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS564201DDCR	null
TPS564208DDCT	null
TPS563249DDCR	null
TPS564208DDCR	null
TPS564201DDCT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20210730004.1		PCN Date:	August 02, 2021																	
Title:	Qualify additional Assembly site for select SOT devices																				
Customer Contact:	PCN Manager		Dept:	Quality Services																	
Proposed 1st Ship Date:	Nov 02, 2021		Estimated Sample Availability:	Provided upon Request																	
Change Type:																					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site																
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material																
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process																
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site																
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials																
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process																
PCN Details																					
Description of Change:																					
<p>Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction differences and current assembly sites are as follows:</p> <p>Group 1 Device:</p> <table border="1"> <thead> <tr> <th colspan="2">SOT-5X3 (DRL)</th> </tr> </thead> <tbody> <tr> <td>Assembly Sites</td> <td>TIPI, HNA, JCETC8, JCETJY, CDAT</td> </tr> <tr> <td>Lead Finish</td> <td>Matte Sn</td> </tr> <tr> <td>Mold Compound</td> <td>4222198 450214 111020003809</td> </tr> </tbody> </table> <p>Group 2 Device:</p> <table border="1"> <thead> <tr> <th colspan="2">SOT-23 (DDC)</th> </tr> </thead> <tbody> <tr> <td>Assembly Sites</td> <td>TIPI, HNA, UTL, JCETC8, JCETJY, CDAT, TIEM</td> </tr> <tr> <td>Lead Finish</td> <td>Matte Sn</td> </tr> <tr> <td>Mold Compound</td> <td>4222198 450207 8097131 120800005407</td> </tr> </tbody> </table>						SOT-5X3 (DRL)		Assembly Sites	TIPI, HNA, JCETC8, JCETJY, CDAT	Lead Finish	Matte Sn	Mold Compound	4222198 450214 111020003809	SOT-23 (DDC)		Assembly Sites	TIPI, HNA, UTL, JCETC8, JCETJY, CDAT , TIEM	Lead Finish	Matte Sn	Mold Compound	4222198 450207 8097131 120800005407
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Reason for Change:																					
Continuity of Supply																					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																					
None																					
Impact on Environmental Ratings																					

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change

Changes to product identification resulting from this PCN:

Assembly Site		
TI Philippines	Assembly Site Origin (22L)	ASO: PHI
Hana	Assembly Site Origin (22L)	ASO: HNT
UTL	Assembly Site Origin (22L)	ASO: NS2
JCETC8	Assembly Site Origin (22L)	ASO: JC8
JCETJY	Assembly Site Origin (22L)	ASO: JCE
TI Chengdu	Assembly Site Origin (22L)	ASO: CDA
TI Melaka	Assembly Site Origin (22L)	ASO: CU6

Sample product shipping label (not actual product label)



Group 1 Product Affected:

TPS562231DRLR	TPS562231DRLT
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Group 2 Product Affected:

SN1501019ADDCR	SN1706011DDCT	TPS54202DDCT	TPS563209DDCT
SN1501019DDCR	SN1708041DDCR	TPS54202HDDCR	TPS563240DDCR
SN1501019DDCT	SN1708041DDCT	TPS54202HDDCT	TPS563240DDCT
SN1501020DDCR	SN1711021DDCR	TPS561201DDCR	TPS563249DDCR
SN1501020DDCT	SN1711021DDCT	TPS561201DDCT	TPS563249DDCT
SN1504025DDCR	SN1711023DDCR	TPS561208DDCR	TPS56339DDCR
SN1504025DDCT	SN1711023DDCT	TPS561208DDCT	TPS56339DDCT
SN1504026DDCR	TPS27081ADDCR	TPS562200DDCR	TPS564201DDCR
SN1504026DDCT	TPS27082LDDCR	TPS562200DDCT	TPS564201DDCT
SN1611045DDCR	TPS54200DDCR	TPS562209DDCR	TPS564208DDCR
SN1702049DDCR	TPS54200DDCT	TPS562209DDCT	TPS564208DDCT
SN1704026DDCR	TPS54201DDCR	TPS563200DDCR	TPS92200D1DDCR
SN1704026DDCT	TPS54201DDCT	TPS563200DDCT	TPS92200D2DDCR
SN1706011DDCR	TPS54202DDCR	TPS563209DDCR	

Group 1 Qualification Report (SOT-5X3)

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	TIPI TLV62568DRL	CDAT TPS562231DRL
TC	Temperature Cycling - 65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C	1000 hours	-	-
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAS T	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0
AC	Autoclave 121C	96 hours	3/231/0	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	JCETC8 TLV62568PDRL	HNA TMP390A2DRL	JCETJY TMP302BDRL
TC	Temperature Cycling - 65/150C	500 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	-	3/231/0
HTSL	Biased HAST 110C/85%RH	264 hours	-	3/231/0	-
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0	3/231/0 (b)
UHA ST	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0	3/231/0
AC	Autoclave 121C	96 hours	3/231/0	-	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0 (a)	3/66/0 (b)
MQ	Manufacturability	-	Pass	Pass	Pass

All qualification devices in the tables are qualified at L1-260C MSL rating.

Note a – Data collected on SN74AVC1T45DRL

Note b – Data collected on TMP102AIDRL and TMP302BDRL

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable

- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

Group 2 Qualification Report (SOT-23)

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	TIPI TPS563249DDC	CDAT TPS563249DDC
TC	Temperature Cycling - 65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C	1000 hours	-	-
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAS T	Unbiased HAST, 130C/85%RH	96 hours	3/231/0	3/231/0
AC	Autoclave 121C	96 hours	-	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (TPS563201DDC)	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	JCETC8 TPS563208DDC	JCETJY TLV62569PDDC
TC	Temperature Cycling - 65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C	1000 hours	-	-
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAS T	Unbiased HAST, 130C/85%RH	96 hours	3/231/0	-
AC	Autoclave 121C	96 hours	-	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0 (TPS27081ADDC)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	UTL LM73CxQDDCRQ 1	TIEM TPL5010QDDCR Q1	HNA LV2862XLVDD C
TC	Temperature Cycling - 65/150C	500 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C	1000 hours	-	3/231/0	-
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0 (a)	-	3/135/0 (b)
UHAST	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0	-
AC	Autoclave 121C	96 hours	3/231/0	-	3/231/0
SD	Solderability	8 Hour Steam	2/44/0 (TPS62242QDDC)	2/44/0 (LM2734XQMK)	3/66/0 (b)

	Stress Test	Duration	UTL LM73CxQDDCRQ 1	TIEM TPL5010QDDCR Q1	HNA LV2862XLVDD C
		age or 155C Dry Bake			
MQ	Manufacturability	-	Pass	Pass	Pass

All qualification devices in the tables are qualified at L1-260C MSL rating.

Note a – Data collected on TPS3702EX33QDDCRQ1 and LM73CxQDDCRQ1

Note b – Data collected on LMP8640QMKX-T/NOPB

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
 - The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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